

FIG. 1

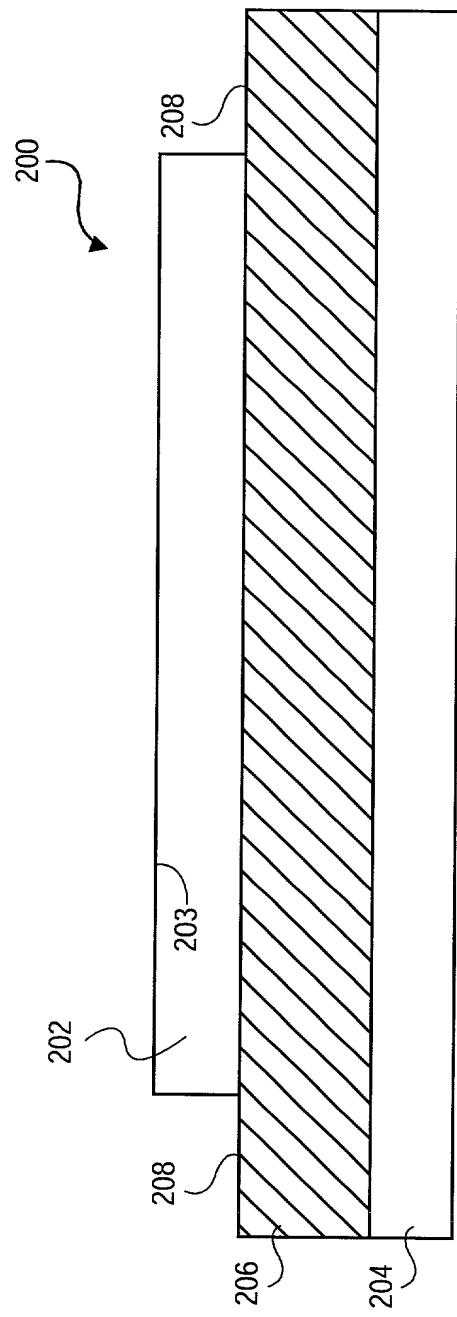


FIG. 2

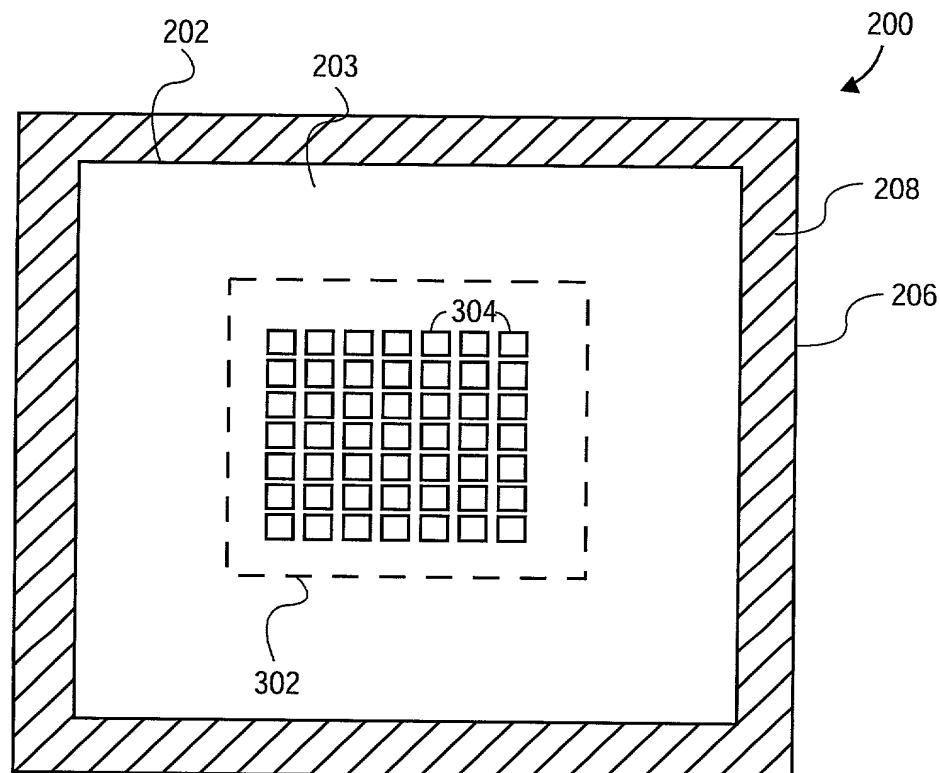


FIG. 3

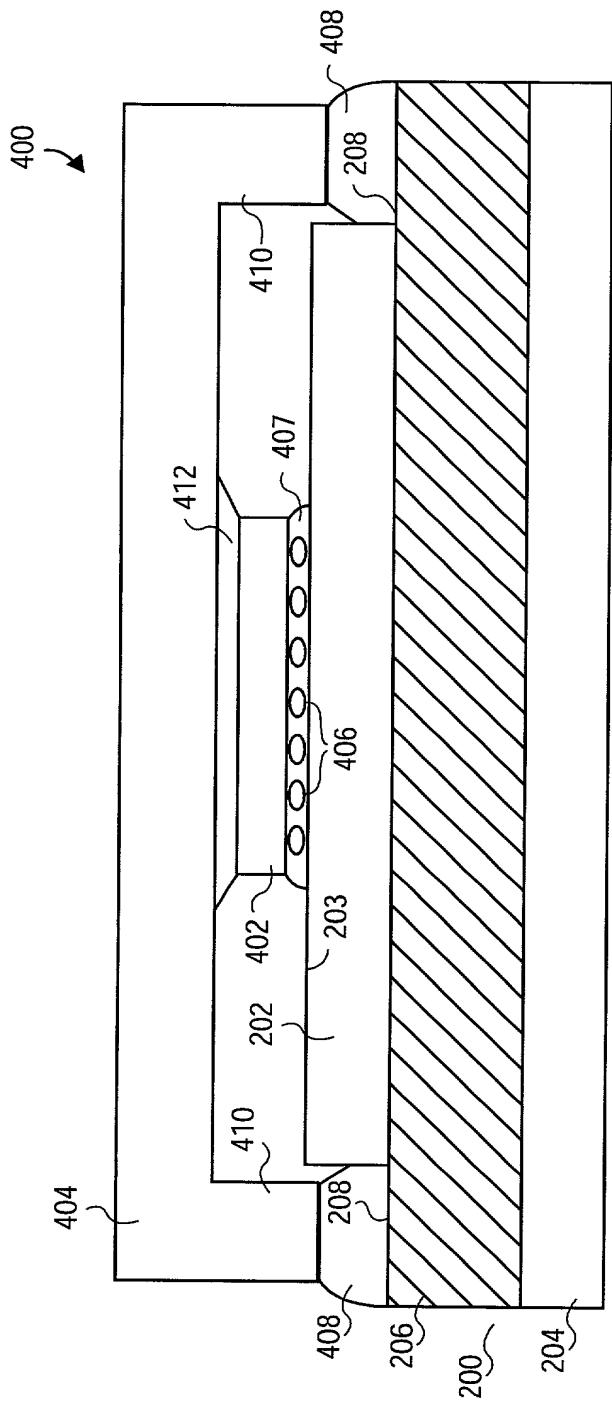


FIG. 4

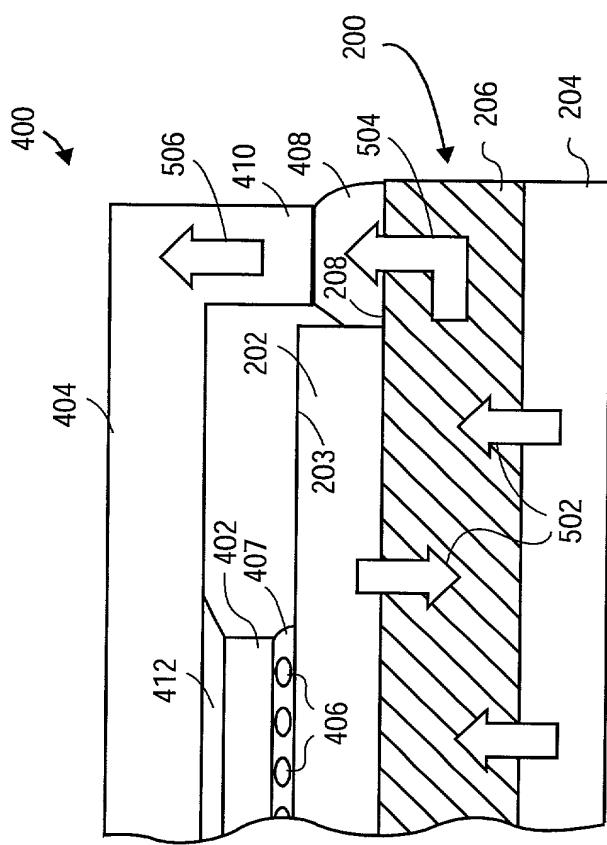


FIG. 5

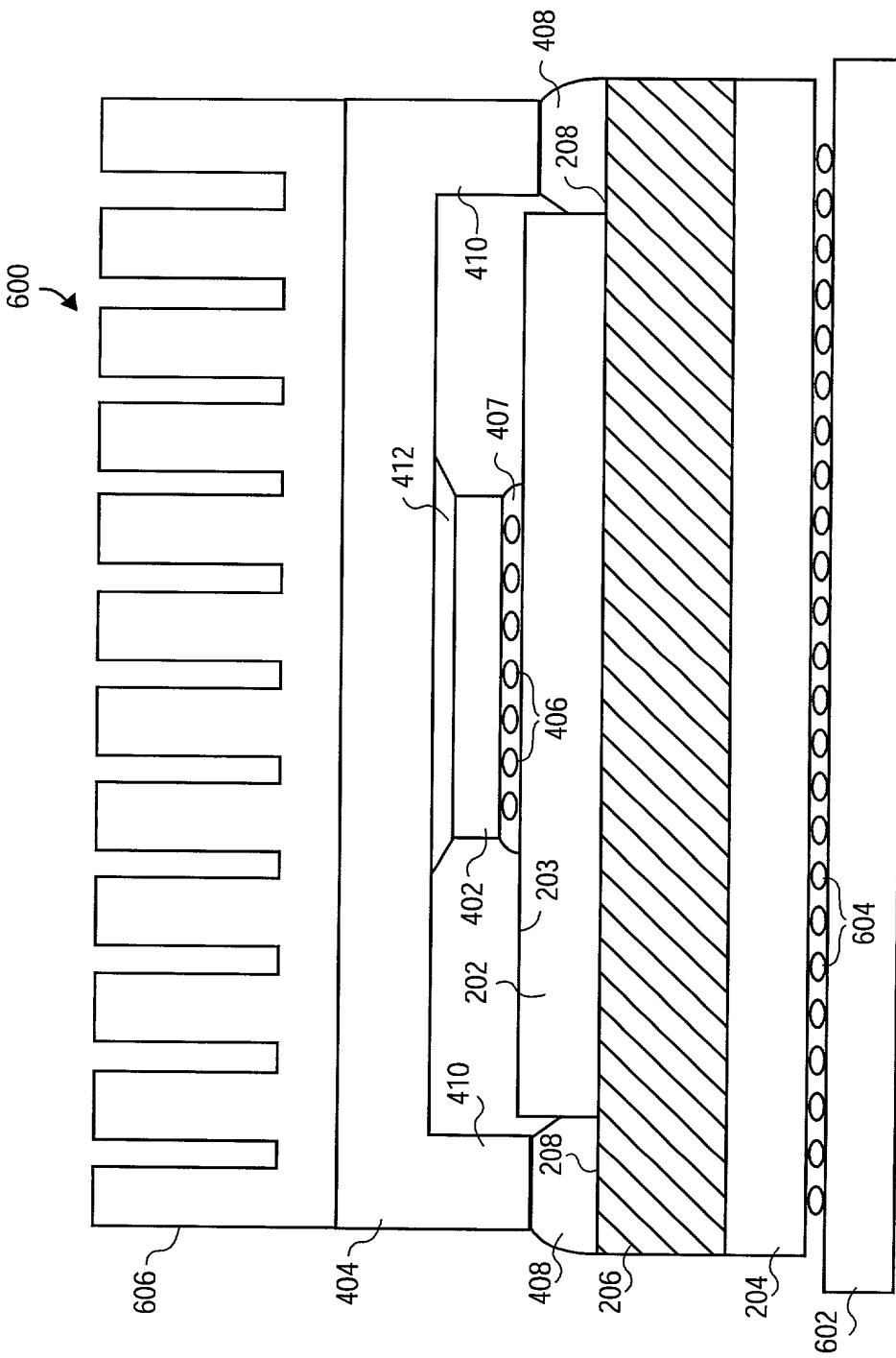


FIG. 6

TITLE: SEMICONDUCTOR PACKAGE WITH INTEGRATED HEAT SPREADER ATTACHED TO A
THERMALLY CONDUCTIVE SUBSTRATE CORE
INVENTOR(S): TIMOTHY M. TAKEUCHI
APPLICATION NO.: 10,038,806

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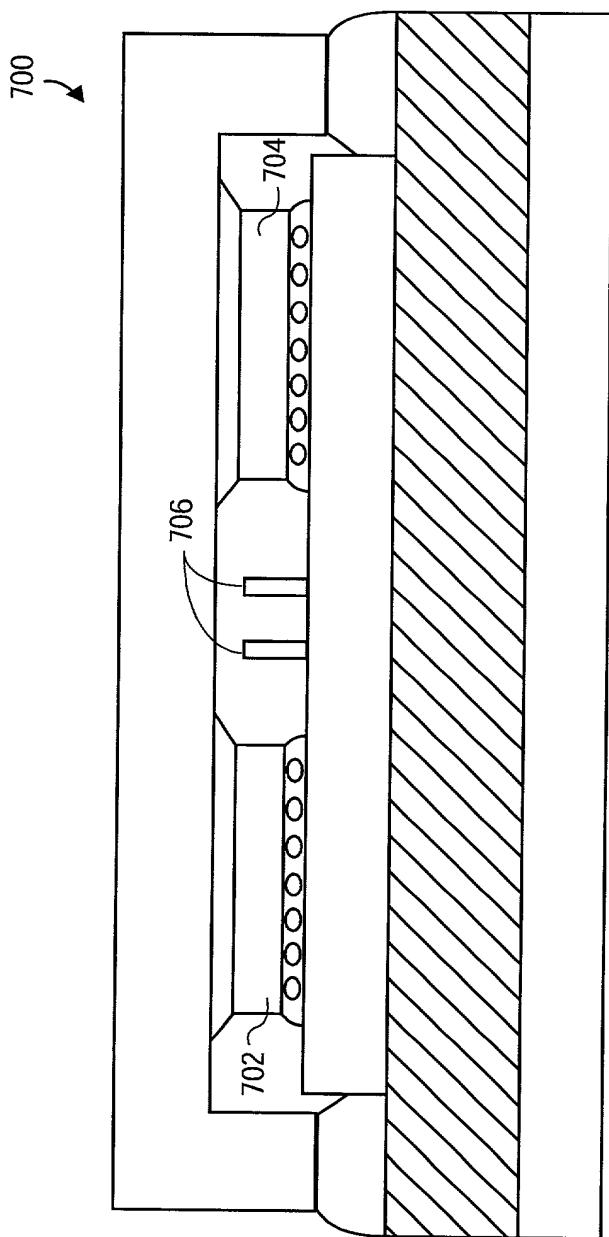


FIG. 7